

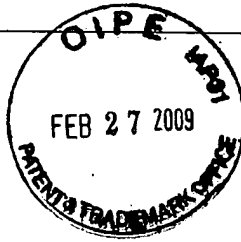
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kazumasa TANIDA et al.

Application No.: 10/594,561

Filed: September 27, 2006

For: SEMICONDUCTOR DEVICE WITH A
SEMICONDUCTOR CHIP CONNECTED IN
A FLIP CHIP MANNER (amended)



Docket No.: AI 427NP

Confirmation No.: 5593

Art Unit: 4116

Examiner: Robert T.W. OWEN

INFORMATION DISCLOSURE STATEMENT (IDS)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is an Information Disclosure Statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(c)(2), i.e., after the mailing of a first Office Action on the merits, but before the mailing date of a final Action or Notice of Allowance.

Listed for consideration on the attached PTO/SB/08 are one U.S patent publication, which was cited in a Chinese office action issued on January 9, 2009 corresponding Chinese application No. 200580014582.8. A copy of the Chinese foreign office action and its English translation are enclosed. Consideration of the listed document is respectfully requested.

It is hereby certified that each item of information contained in this Information Disclosure Statement was first cited in a communication from a foreign patent office in connection with a counterpart foreign application not more than three months prior to the filing of this statement.

The Director is hereby authorized to charge any deficiency in the fees filed, asserted to be filed or which should have been filed herewith to our Deposit Account No. 18-0002, under Order No. AI 427NP.

Dated: February 27, 2009

Respectfully submitted,

By


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ALP/pq